

Amendments to the Abstract:

Please amend the Abstract as follows:

ABSTRACT OF THE DISCLOSURE

~~A method for preventing or reducing warping of a~~ A semiconductor wafer ~~following backside grinding to having~~ a high degree of thinness ~~and exhibiting an enhanced strength state.~~ Following ~~rough backside grinding of the wafer,~~ a A layer of tenacious reinforcement material is ~~applied-disposed over the rough,~~ a back side of the wafer while in a rough state from ~~backgrinding~~ without prior, conventional polishing or plasma etching ~~of the back side.~~ The thin layer or film of reinforcement material ~~is applied and hardened to fill~~ fills grooves, fractures and scratches in the back side of the wafer, enhance the rigidity of the wafer and provide a planar, smooth, back side surface layer. The ~~hardened~~ reinforcement material counteracts internal stresses of the wafer tending to warp, crack and propagate lattice defects in the wafer. The reinforcement material may also be configured to act as a die attach adhesive, may provide an ionic barrier, and may remain as part of the packaging for semiconductor dice singulated from the wafer.